

High Conductivity Aluminum Diamond Heat Spreader AS-D60

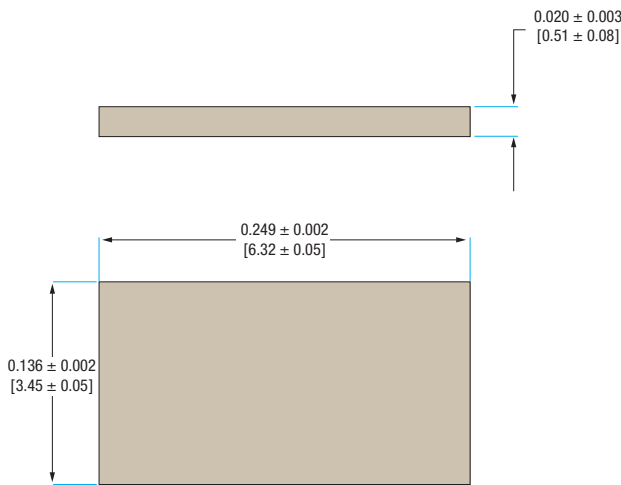
for Industrial, Space and Aerospace Applications



Product Sales Sheet

Validity: January 1, 2017 - March 31, 2017

Al-Diamond Dimensions & Tolerances



BENEFITS

- Thermal conductivity reaching 500 W/mk
- CTE matched to various semiconductor materials
- Heat spreaders provided with Ni/Au electrolytic or electroless plating

AL-DIAMOND AS-D60 MATERIAL PROPERTIES*

Thermal Conductivity (RT):

≥ 450 W/mK (thickness ≥ 0.76mm to 1.3mm)

Thermal Conductivity (RT):

≥ 500 W/mK (thickness ≥ 1.3mm)

Thermal Expansion (RT-400°C):

$8.0 \times 10^{-6}/K \pm 0.5$ (thickness ≥ 0.76mm to 1.0mm)

Thermal Expansion (RT-400°C):

$7.6 \times 10^{-6}/K \pm 0.5$ (thickness ≥ 1.00mm to 1.30mm)

Thermal Expansion (RT-400°C):

$7.2 \times 10^{-6}/K \pm 0.5$ (thickness ≥ 1.30mm)

Density: 3.10 g/cc to 3.26g/cc

Specific Heat: 0.62 J/gK

Flexural Strength: 300 MPa

Modulus: 340 GPa

Electrical Conductivity: $\leq 3.7 \times 10^{-7}$ ohm•m

**Typical properties. Actual results may vary*

NMIC P/N	DESCRIPTION	MIN QTY	MAX QTY	PRICE
64-W5732C01A	Al-Diamond AS-D60, 0.249" x 0.136" x 0.020" Ni/Au Plated (4.0 micron Nickel, 2.0 Micron Gold)	100	199	\$137.68
64-W5732C01A	Al-Diamond AS-D60, 0.249" x 0.136" x 0.020" Ni/Au Plated (4.0 micron Nickel, 2.0 Micron Gold)	200	500	\$70.61

Shipping and handling apply. Export restrictions may apply based on end country and application.

